



# SOT102-1

plastic dual in-line package; 18 leads (300 mil)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DIP18
<b>Package type industry code</b>	DIP18
<b>Package style descriptive code</b>	DIP (dual in-line package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-001
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	13-2-2003

Table 1. Package summary

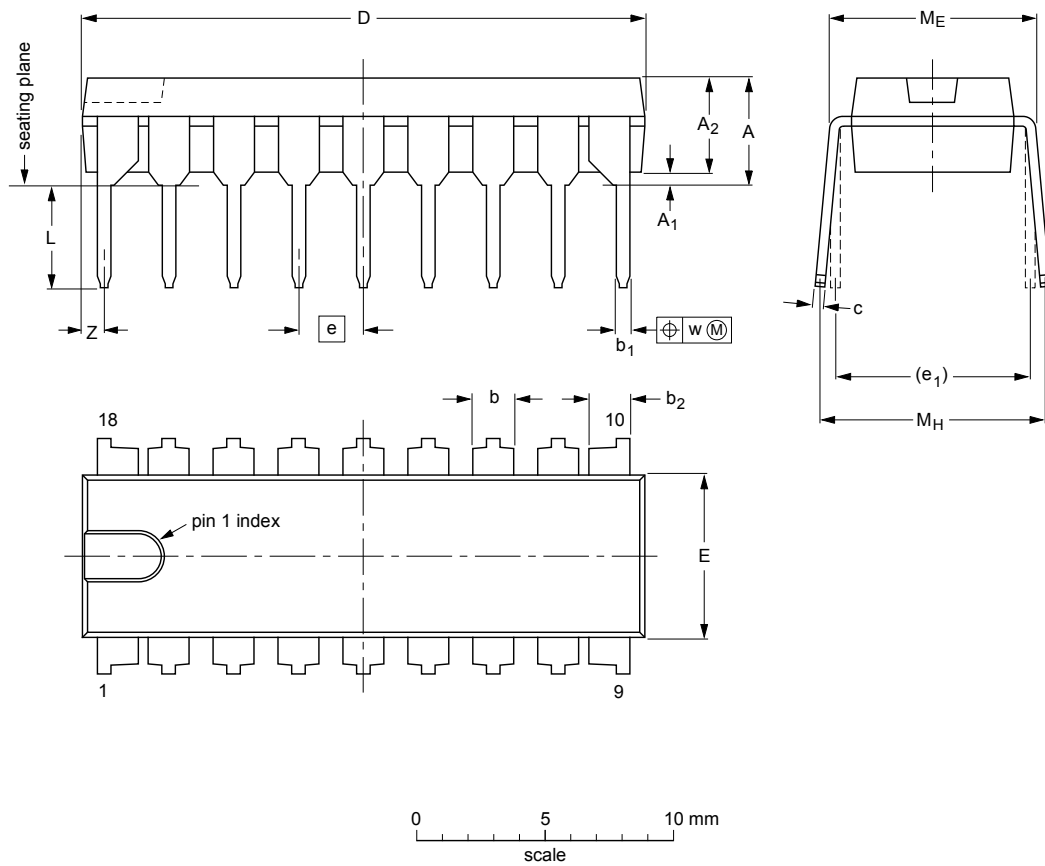
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.4	-	21.6	21.8	mm
E	package width	6.2	-	6.34	6.48	mm
A	seated height	[tbd]	-	[tbd]	4.7	mm
A <sub>2</sub>	package height	[tbd]	-	[tbd]	3.7	mm
e	nominal pitch	-	-	2.54	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	18	-	



## 2. Package outline

DIP18: plastic dual in-line package; 18 leads (300 mil)

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	1.40 1.14	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	0.85
inches	0.19	0.02	0.15	0.055 0.044	0.021 0.015	0.055 0.044	0.013 0.009	0.86 0.84	0.26 0.24	0.1	0.3	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.033

**Note**

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT102-1		MS-001				99-12-27 03-02-13

Fig. 1. Package outline DIP18 (SOT102-1)

### 3. Legal information

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## 4. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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